

Appl. No. : **10/618,957**
Filed : **July 14, 2003**

AMENDMENTS TO THE CLAIMS

Please amend the claims as follows.

1-9 (Canceled)

10 (Currently Amended): The transparent surface protective film of Claim 238, wherein the thickness of said adhesive layer is about 3-100 μm .

11 (Currently Amended): The transparent surface protective film of Claim 238, wherein the thickness of said adhesive layer is about 5-40 μm .

12 (Currently Amended): The transparent surface protective film of Claim 238, wherein said base material film comprises polyethylene terephthalates and/or polyethylene naphthalates.

13 (Withdrawn - Currently Amended): A transparent conductive substrate comprising a substrate and the surface protective film of Claim 238 attached on a surface of the substrate.

14 (Canceled)

15 (Currently Amended): The transparent surface protective film of Claim 238, consisting of:

the transparent base material film,

the transparent adhesive layer formed on one side of the base material film, and

the transparent antistatic layer formed on the other side of the base material film.

16 (Withdrawn): A method for protecting a transparent conductive substrate surface, comprising:

providing a transparent surface protective film comprising a transparent pressure-sensitive adhesive layer on one side of a transparent base material film and a transparent antistatic layer on the other side of the transparent base material film, said transparent antistatic layer comprising polymers having pyrrolidinium rings as multiple repeating units in main chains thereof, and

attaching said transparent surface protective film to a transparent conductive substrate which comprises a conductive thin film, wherein said transparent surface protective film is attached to a surface of the side of the transparent conductive substrate to which the conductive thin film is attached, or said transparent surface protective film is attached to an opposite side of the side of the transparent conductive substrate to which the conductive thin film is attached,

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wherein the transparent surface protective film maintains transparency after heat treatment at 150 °C.

17 (Withdrawn): The method of Claim 16, further comprising:

heating to a temperature range of 90°C to 150°C said transparent surface protective film attached to said transparent conductive substrate, wherein the transparent surface protective film maintains transparency throughout said heat treatment.

18 (Canceled)

19 (Currently Amended): The transparent surface protective film of Claim 238, wherein the adhesive layer comprises a co-polymer containing 0.1 through 12 percent by weight of monomers having functional groups selected from carboxyl groups, hydroxyl groups, epoxy groups and amino groups.

20. (Currently Amended): The transparent surface protective film of Claim 238, wherein the transparent base material film is a single-layer film.

21-22. (Canceled)

23. (Currently Amended): ~~The transparent surface protective film of Claim 8A~~
transparent surface protective film for transparent conductive substrates protecting a surface opposite to a side of a conductive thin film of the transparent conductive substrates or a surface on a side of the conductive thin film, comprising:

a transparent base material film,

a transparent adhesive layer formed on and in contact with one side of the base material film, and

a transparent antistatic layer formed on and in contact with the other side of the base material film,

said transparent surface protective film being configured to maintain transparency even after one-hour heat treatment at 150°C,

wherein the antistatic layer comprises polymers having pyrrolidinium rings as multiple repeating units in main chains thereof, and wherein the antistatic agent is polymers having pyrrolidinium rings are blended with a polyvinyl alcohol-based polymer.